

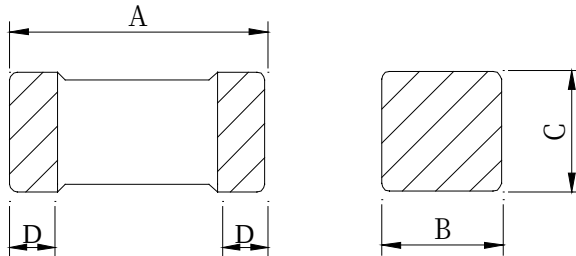
SPECIFICATION FOR APPROVAL

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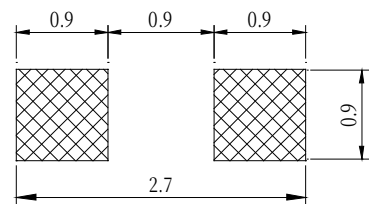
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PROD. NAME	WOUND CHIP INDUCTOR	ABC'S DWG NO.	SL1608□□□□L□
		ABC'S ITEM NO.	

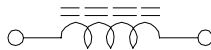
I . CONFIGURATION & DIMENSIONS :



A	: 1.6±0.2	m/m
B	: 0.8±0.2	m/m
C	: 0.8±0.2	m/m
D	: 0.4 typ.	m/m

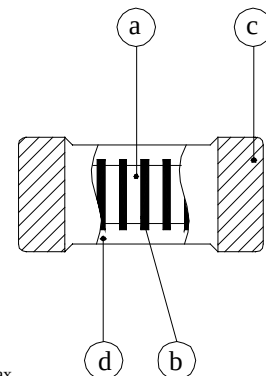


II . SCHEMATIC DIAGRAM :



III . MATERIALS :

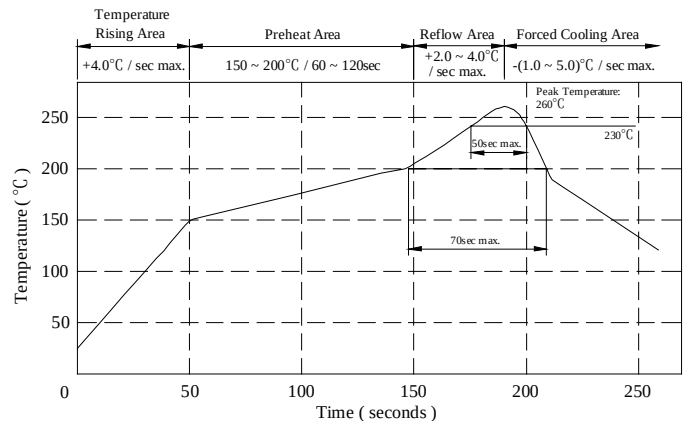
- a . Core : Ceramic
- b . Wire : Copper
- c . Terminal : Solder coat over Ni plate (Lead content 100ppm max.)
- d . Coating : Epoxy resin
- e . Remark : Lead content 2100 ppm typ.
include ceramic



Peak Temp : 260°C max.
Max time above 230°C : 50sec max.
Max time above 200°C : 70sec max.

IV . GENERAL SPECIFICATION :

- a . Temp rise : 15°C max
- b . Rated current : Current cause inductance drop within 10% max.
- c . Storage temp. : -40°C ----+125°C
- d . Operating temp. : -40°C ----+105°C
- e . Resistance to solder heat : 260°C.10 secs.



AE-001A

ABC 千如電子集團
ABC ELECTRONICS GROUP.

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V . ELECTRICAL CHARACTERISTICS :

DWG No.	Inductance (nH)	Q min	Test Freq. (MHz)		SRF (MHz) min	RDC (Ω) max	IDC (mA) max
			L	Q			
SL16081N0ML□	1.0±20%	7	100	100	6000	0.05	500
SL16081N2ML□	1.2±20%	7	100	100	6000	0.06	500
SL16081N5ML□	1.5±20%	8	100	100	6000	0.07	500
SL16081N8ML□	1.8±20%	8	100	100	6000	0.08	500
SL16082N2ML□	2.2±20%	8	100	100	6000	0.09	500
SL16082N7ML□	2.7±20%	8	100	100	6000	0.10	500
SL16083N3ML□	3.3±20%	9	100	100	5500	0.12	500
SL16083N9JL□	3.9± 5%	9	100	100	5500	0.15	450
SL16084N7JL□	4.7± 5%	9	100	100	4800	0.17	450
SL16085N6JL□	5.6± 5%	9	100	100	4600	0.18	430
SL16086N8JL□	6.8± 5%	9	100	100	3550	0.20	430
SL16088N2JL□	8.2± 5%	9	100	100	3500	0.28	400
SL160810NJL□	10.0± 5%	10	100	100	2800	0.32	400
SL160812NJL□	12.0± 5%	10	100	100	2800	0.35	400
SL160815NJL□	15.0± 5%	10	100	100	2500	0.41	350
SL160818NJL□	18.0± 5%	10	100	100	2300	0.45	350
SL160822NJL□	22.0± 5%	10	100	100	2000	0.50	300
SL160827NJL□	27.0± 5%	10	100	100	2000	0.55	300
SL160833NJL□	33.0± 5%	10	100	100	1800	0.60	300
SL160839NJL□	39.0± 5%	11	100	100	1800	0.80	300
SL160847NJL□	47.0± 5%	11	100	100	1800	0.95	250
SL160856NJL□	56.0± 5%	12	100	100	1800	1.20	250
SL160868NJL□	68.0± 5%	12	100	100	1500	1.30	250
SL160882NJL□	82.0± 5%	12	100	100	1500	1.50	250
SL1608R10JL□	100.0± 5%	12	100	100	1300	1.80	200
SL1608R12JL□	120.0± 5%	5	25.2	25.2	1200	3.00	130
SL1608R15JL□	150.0± 5%	5	25.2	25.2	1100	4.50	100
SL1608R18JL□	180.0± 5%	4	25.2	25.2	1000	6.50	80
SL1608R22JL□	220.0± 5%	4	25.2	25.2	900	7.50	70

1). □ : Packaging Information... ☐ Bulk ☐ Taping Reel

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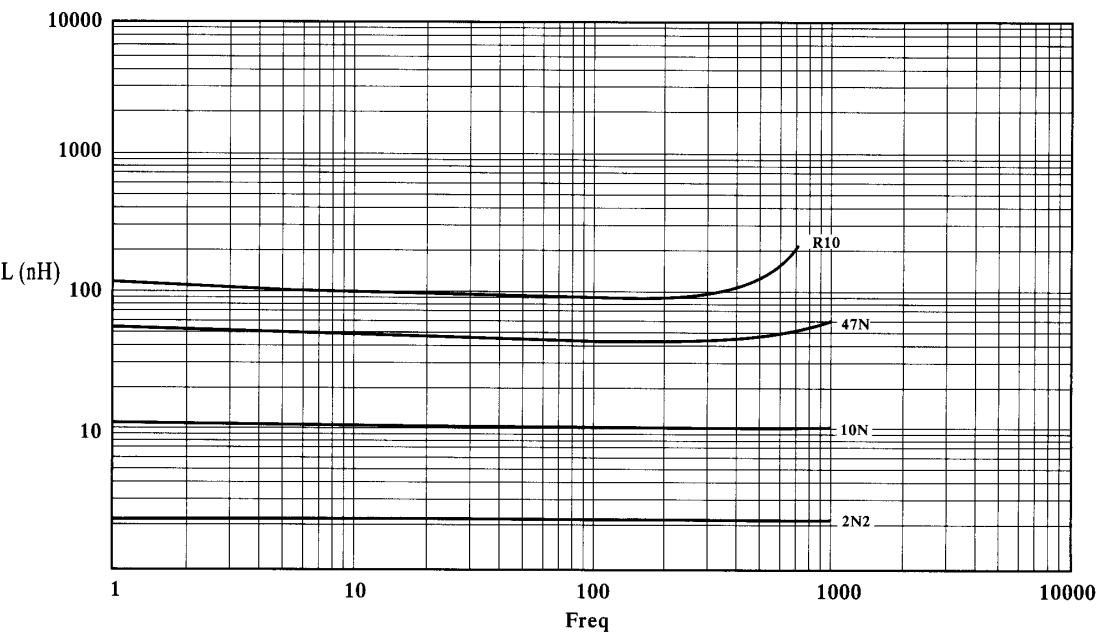
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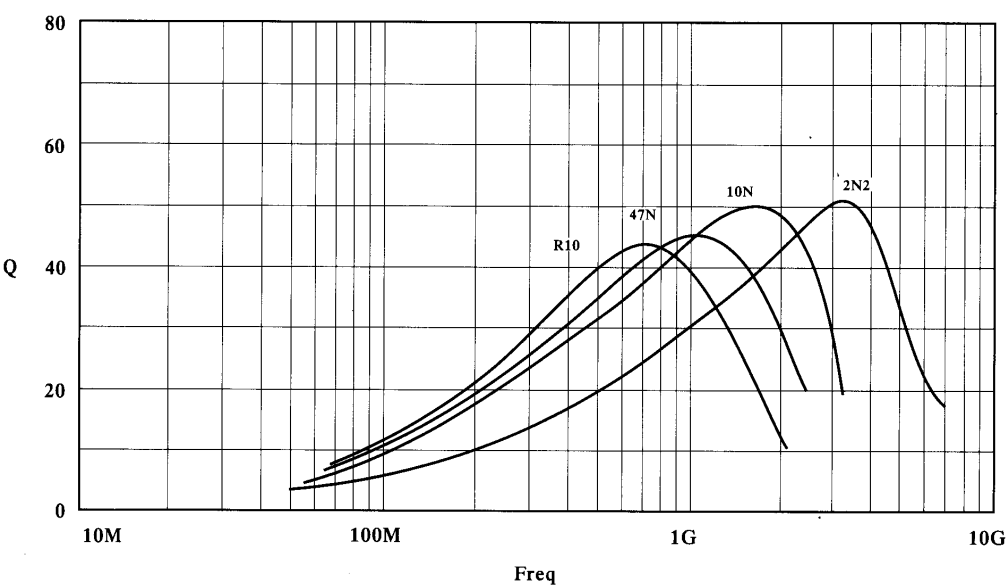
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VI . CURVE :

L vs Freq Plot



Q vs Freq Plot



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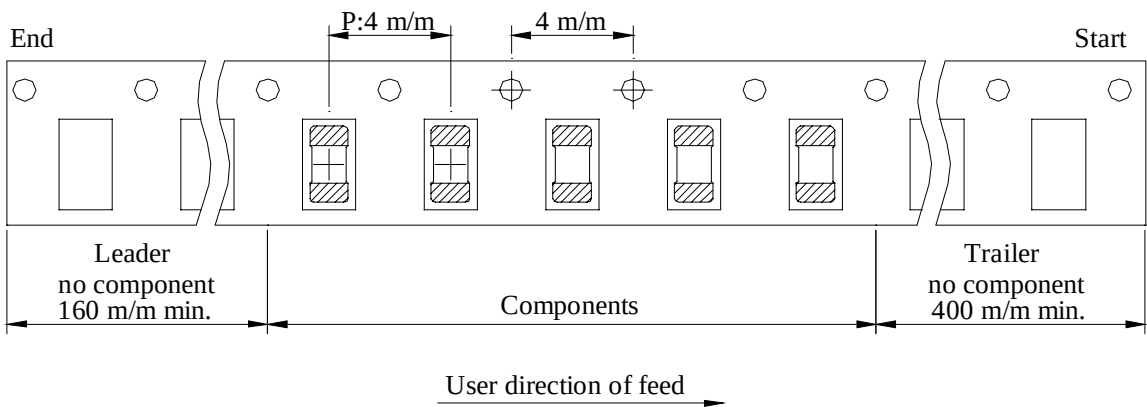
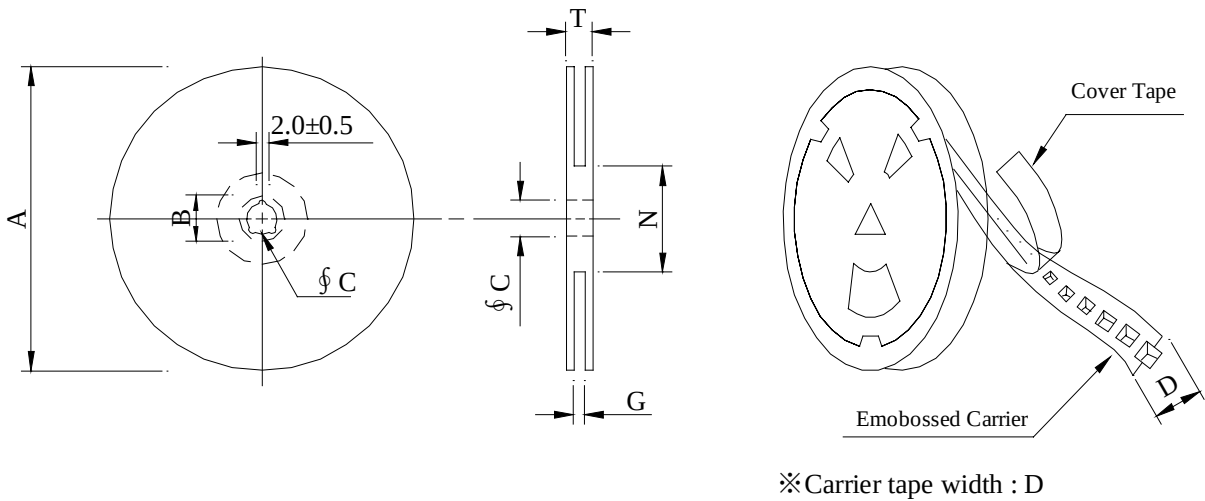
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VII . PACKAGING INFORMATION :

(1) Configuration



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10 ⁺⁰	50 ⁻⁰	12.5

(3) Q'TY & G.W. Per package

Series	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY (pcs)	G.W. (Kg)	Size (cm)
SL1608	3,000	100	07 - 08	150,000	5.50	41 x 39 x 22

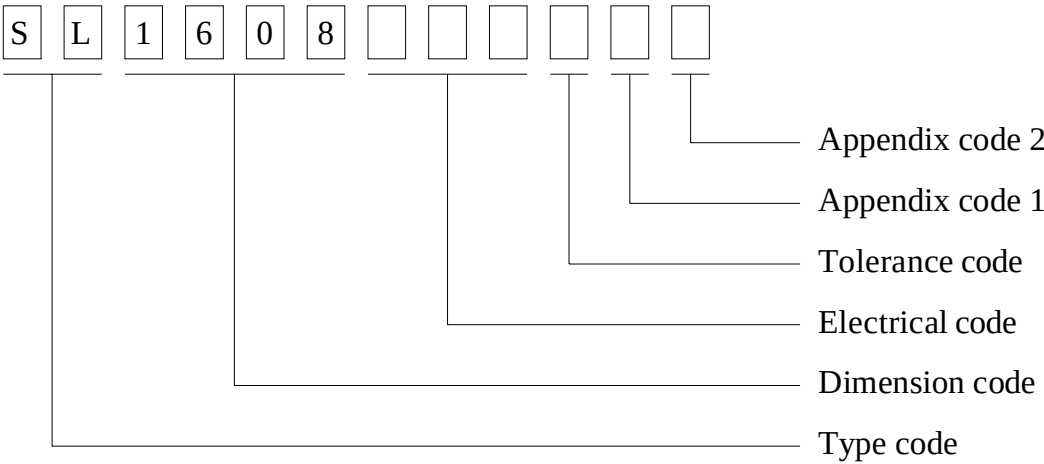
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VIII . DWG EXPRESSION :



Appendix code 1 : S : Standard products
A K, M R, T Z : Special products
L : Standard Lead Free products
1 ~ 9 : Special Lead Free products

Appendix code 2 :

Code	Inner package	Inner package Q'TY	Remark
A	Empty	EMPTY	
B	T / R (Reel package)	3000 pcs	

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IX . RELIABILITY TEST :

Test item	Specification	Test condition
Solderability	More than 90% of the terminal electrode Shall be covered With fresh solder.	Preheat : $150\pm 25^{\circ}\text{C}$ for 60 seconds Solder : Sn96.5 / Ag3 / Cu0.5 or equivalent Solder temp. : $235\pm 5^{\circ}\text{C}$ Flux : Rosin Dip time : 4 ± 1 seconds
Thermal shock test (Temp. cycle)	Inductance shall not change more than $\pm 30\%$	Room temp. $\longrightarrow$ $-25\pm 2^{\circ}\text{C}$ 15 minutes $\longrightarrow$ 30 minutes Room temp. $\longrightarrow$ $85\pm 2^{\circ}\text{C}$ 15 minutes $\longrightarrow$ 30 minutes Total : 50 cycles
Humidity Resistance test		Temperature : $40\pm 2^{\circ}\text{C}$ Humidity : 90 ~ 95% Applied current : Per spec. Time : 500 hours
High temp. Resistance test		Temperature : $105\pm 2^{\circ}\text{C}$ Applied current : Per spec. Time : 500 hours